

ENGINEERING DEPT.		PRODUCT SPECIFICATION	SPEC.NO.:	SPCI143A
REVISIONS	ECNT116090	For CI63 Connectors	PAGE:	1/4

1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and below standards base on CviLux test procedure

2. APPLICABLE STANDARDS:

MIL - STD - 202	Methods for test of connectors for electronic equipment
MIL - STD - 1344	Test methods for electrical connectors
J-STD-020	Resistance to soldering Temperature for through hole Mounted Devices
SS-00254	Test methods for electronic components ,LEAD-FREE soldering Part design
	standards

3. APPLICABLE SERIES NO.: CI63**M*VR0-NH CI63**S0000 CI63T01*PP0

4. SHAPE, CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

See attached drawings

6. ACCOMMODATED P.C.BOARD: 1.6 mm (.063")



REVIEWED : <u>Eisley</u> APPROVED : <u>Clark</u> VERIFIED : <u>Clark</u> .



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7. ELECTRICAL PERFORMANCE:						
	ITEM			TEST CONDITION		
7.1	Rated current and voltage				2.0A 50V AC/DO	2
7.2	Contact resistance		Dry	circuit of DC 20 mV max. 10 mA max.	Less than 20	mΩ
7.3	Dielectric strength			en applied AC 500 V 1 minute between acent terminal	No change	
7.4	Insulation resistance			en applied DC 500 V between adjacent ninal or ground	More than 1	00 MΩ
7.5				np the applicable wire on to the terminal usure by dry circuit 20mV Max. 10mA	Less than 10	mΩ

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION		REQUIREMENT
8.1	Terminal crimp Tensile	When crimped AWG#28 size w	More than 1.0 Kgf	
	strength	When crimped AWG#30 size w	More than 0.8 Kgf	
8.2	Pin retention force	Push pin from insulator base at speed 25 ± 3 mm per minute		More than 100 gram
8.3	Terminal retaining force in insulator	Retention speed 25± 3 mm per minute from housing		More than 0.40 Kgf
8.4	Terminal insertion force in insulator	Insertion speed 25± 3 mm per minute from housing		Less than 0.50 Kgf
8.5	Mating & Unmating Force	Speed 25± 3 mm per minute Mating		2P: Less than 1.84 kgf3P: Less than 2.14 kgf4P: Less than 2.45 kgf5P: Less than 2.76 kgf
			Unmating	2~5P: More than 0.12 kgf
8.6	Durability	Connector shall be subjected to 50 cycles of insertion and withdrawal		Contact resistance: Less than 20 mΩ

9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Temperature rise	Then carried the rated current	30°C max.



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	ITEM			TEST CONDITION	REQUIREMENT	
9.2	Vibration		1.5 mm 10 - 55 - 10 HZ/minute each 2 hours for X,Y and Z directions		Appearance: No damageContact resistance:Less than 20 mΩDiscontinuity:1 micro second max.	
9.3	Shock		490m/s ² {50G}, 3 strokes in each X,Y,Z axes		Appearance: No damageContact resistance:Less than 20 mΩDiscontinuity:1 micro second max.	
9.4	Solder ability		Lead-Free Process: Soldering time: 3 ± 0.5 second Soldering pot: 245 ± 5°C		Minimum: 95% of immersed area	
9.5	Resistance to soldering heat			d-Free Process for SMT Type: er Reflow temperature profile(11.1)	No damage	
9.6	Heat aging		85±	: 2°C, 96 hours	Appearance: No damage Contact resistance: Less than 20 mΩ	
9.7	Cold Resistance		-25:	± 5°C, 96 hours	Appearance: No damage Contact resistance: Less than 20 m Ω	
9.8	Humidity		mea	2°C, 90-95% RH, 96 hours asurement must be taken within 30 min. r tested	Appearance: No damage Contact resistance: Less than 20 mΩ Dielectric strength: Must meet 7.3 Insulation resistance: More than 100 MΩ	
9.9			 (1) (2)F (3) (4)F 	e cycle consists of : -55_{-3}^{+0} °C , 30 min. Room temp. 10-15 min. 85_{-0}^{+3} °C , 30 min. Room temp. 10-15 min. al cycle: 10 cycle	Appearance: No damage Contact resistance: Less than 20 mΩ	



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	ITEM TES		EST CONDITION	REQUIREMENT			
9.10	Salt spray]	emperature: 35± 3°C	Appearance: No damage			
	Solu		olution: 5± 1%	Contact resistance:			
	Spra		pray time: 48± 4 hours	Less than 20 m Ω			
			easurement must be taken after water nse				

- 10. AMBIENT TEMPERATURE RANGE: -25 to + 85°C
- 11. Recommended IR Reflow Temperature Profile: 11.1 Using Lead-Free Solder Paste

